RF IPD products for STM32WL: how to pick the right product





Note: * Qualification Q2 2024, ** Qualification Q4 2024

RF IPD products for Bluetooth® Low Energy chips



Direct match of STM32WB impedance

Deep attenuation to answer system requirements

How to pick the right product

		10 dbm 2400 MHz		
		4 Layers	2 Layers	
STM32WBxx	STM32WBxx BGA and CSP	MLPF-WB-02D3		
	STM32WBxx QFN		MLPF-WB-01D3	
STM32WBA	STM32WBAxx BGA STM32TWBAxx QFN	MLPF-WB-04D3		
STM32WB09	BLUENRG-LP-LPS	MLPF-N	MLPF-NRG-01D3	
BlueNRG-1/-2	BLUENRG-1 and BLUENRG-2 (QFN and CSP)	BALF-NRG-02D3		
BlueNRG-MS	BLUENRG-MS (QFN andCSP)	BALF-NRG-01D3		



Wireless connectivity - RF IPD



Protection and EMI filters

Protection and Filters IPD-RF



ន្ម ST companion-chips



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The stressful life of an IC



An IC rated according to the human body model (HBM) is not protected against external electrostatic discharge (ESD) events. The energy carried by IEC61000-4-2 is much higher than that of HBM. Only an external ESD protection rated according to IEC standards can clamp the IEC61000-4-2 Level 4 (+8kV) ESD surge.

ESD and EOS standards EOS ESD Electrostatic discharge System level System level Component level To ensure To simulate To ensure manufacturability robustness car behavior IEC 61000-4-2 CDM ISO10605 ISO7637 luman boo (automotive) ISO16750 model model device mode Final user simulation These standards have low-level surges as factories System robustness for end users. are well-controlled environments. Uncontrolled environment.

To ensure compliance with the most stringent requirements, ST ESD protection and EMI filter devices combine:

- Protection efficiency with low clamping voltage (VCL)
- Protection transparency with low leakage current (IRM)
- Signal integrity with ultralow capacitance and ultrawide bandwidth



- Best-in-class performance
- 10-year longevity commitment
- Referenced in ST hardware boards

Recommended Protection and Filters around MCUs



Standard packaging options are available as well as advanced options, which include single- and multiple-line, compact, flat, and flow-through versions to optimize space constraints. Visit our site.

RF IPD solution: integration and performances



Covering all RF applications with a frequency range from 168 MHz and above, including sub-GHz, WLAN, Bluetooth, ZigBee, WiMax, UWB, LTE, and more, ST integrated passive devices (IPD) offer competitive cost structure, a small form factor, and reduced power losses.

Key benefits

- Design simplification
- Performance optimization
- System integration
- Reliability improvement
- BOM reduction
- Customized designs



RF IPD products for long range chips: STM32WL5, STM32WL3, SPIRIT1 and SPIRIT2

APPLICATION

Smart Tracking





Metering



Alarm System



Antenna

sigfox

All in one: matching, deep filtering, balun, and antenna protection. Tx matching Tx filter Z Various RF IPD part numbers to match RF chip modes and packages



RF IPD for SPIRIT1 and SPIRIT2 chips: how to pick the right product

	High power mode High frequency band		Low power mode Low frequency band	
	4 Layers	2 Layers	4 Layers	2 Layers
Spirit1	BALF-SPI-01D3		BALF-SPI-02D3	
Spirit2	BALF-SPI2-01D3	BALF-SPI2-03D3	BALF-SPI2-02D3	